Z21 These assemblies are ESD sensitive, ESD precautions shall be observed.
Z22 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
Z23 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Components marked 'DNP' should not be populated.
Assembly variant: 001
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